

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
SANG TAE AHN	02/25/2008
JA CHUN KU	02/25/2008
EUN JEONG KIM	02/25/2008
<b>RECEIVING PARTY DATA</b>	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si
City:	Kyongki-do
State/Country:	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	12045073
<b>CORRESPONDENCE DATA</b>	
Fax Number:	(312)427-6663
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	3124271300
Email:	nicholas.kubacki@ladas.net
Correspondent Name:	RICHARD J. STREIT
Address Line 1:	LADAS & PARRY, 224 SOUTH MICHIGAN AVE.
Address Line 4:	CHICAGO, ILLINOIS 60604
ATTORNEY DOCKET NUMBER:	CU-6415 WWP/NK
NAME OF SUBMITTER:	Woochoon W. Park
Total Attachments: 2 source=cu6415assign#page1.tif source=cu6415assign#page2.tif	

CH \$40.00 12045073

---

**UNITED STATES OF AMERICA**  
**ASSIGNMENT**

---

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

**ASSIGNOR:**

Name : Sang Tae AHN

Address : 101-605, Hyundai I-PARK Apt., Sadong-ri, Daewol-myeon, Icheon-si, Gyeonggi-do, Korea

Name : Ja Chun KU

Address : 303-1205, Halla Apts., Cheongsolmaeul, Geumgok-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea

Name : Eun Jeong KIM

Address : 202-302, Buyung Apt., Moonsu-dong, Yeosu-si, Jeollanam-do, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

**ASSIGNEE:**

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

METHOD FOR FORMING DEVICE ISOLATION STRUCTURE OF SEMICONDUCTOR DEVICE  
USING ANNEALING STEPS TO ANNEAL A FLOWABLE INSULATION LAYER

(TITLE)

and which is found in *(check one applicable item below)*

U.S. patent application executed on even date herewith

U.S. Application Serial No. \_\_\_\_\_ filed on \_\_\_\_\_

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

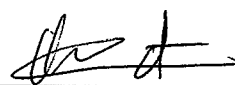
ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

February 25, 2008

Date



INVENTOR: Sang Tae AHN

February 25, 2008

Date



INVENTOR: Ja Chun KU

February 25, 2008

Date



INVENTOR: Eun Jeong KIM

0699P/1